

SAD
#3B
9-15-00

PATENT
Atty. Dkt. No. AMAT/3421.C1/ISM/COPPER/DV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Cheung, et al. §
Serial No.: ~~Unknown~~ 09/609347 §
Filed: ~~Herewith~~ 7-5-00 §
For: Apparatus for Electro Chemical §
Deposition of Copper Metallization §
With the Capability of In-Situ §
Thermal Annealing §

Group Art Unit: ~~Unknown~~ 1741
Examiner: ~~Unknown~~ HIC/CS

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING 37 C.F.R. 1.10	
I hereby certify that this correspondence is being deposited on 7/5, 2000, with the United States Postal Service as Express Mail No. EL635441628US, in an envelope addressed to: Assistant Commissioner for Patents, Box PATENT APPLICATION, Washington, D.C. 20231.	
Date 7/5/2000	Signature B. John Patton

PRELIMINARY AMENDMENT

Applicants request entry of the following amendments prior to consideration of the claims pending in the application.

IN THE CLAIMS:

Please amend the claims as follows:

- B1
Sub C17
1. (Amended) An electro-chemical deposition system, comprising:
- a) a mainframe having a mainframe wafer transfer robot;
 - b) a loading station disposed in connection with the mainframe;
 - c) one or more [processing] electrochemical deposition cells disposed in connection with the mainframe; and